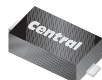
Material Composition Specification

SOD-923 Case



Device average mass . . . . 0.5 mg
Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	7.5%	0.037	Si	7440-21-3	7.5%	0.0375	74,970
bond wire	gold	0.76%	0.004	Au	7440-57-5	0.76%	0.0038	7,597
leadframe	copper w/ silver plating	47.14%	0.236	Cu	7440-50-8	45.98%	0.23	459,816
				Ag	7440-22-4	1.16%	0.0058	11,595
encapsulation*	EMC	42.14%	0.211	silica	7631-86-9	30.39%	0.152	303,878
				epoxy resin	Proprietary	10.6%	0.053	105,958
				Sb_2O_3	1309-64-4	0.84%	0.0042	8,397
				TBBA	79-94-7	0.22%	0.0011	2,199
				carbon	1333-86-4	0.1%	0.0005	1,000
	EMC GREEN	42.14%	0.211	silica	60676-86-0	28.17%	0.141	281,682
				epoxy resin	29690-82-2	6.4%	0.032	63,979
				phenol resin	9003-35-4	3.21%	0.016	32,099
				carbon black	1333-86-4	0.22%	0.001	2,184
				metal hydroxide	1309-42-8	4.15%	0.021	41,488
plating	matte tin	2.46%	0.012	Sn	7440-31-5	2.46%	0.0123	24,590

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.